Status of Compute Node

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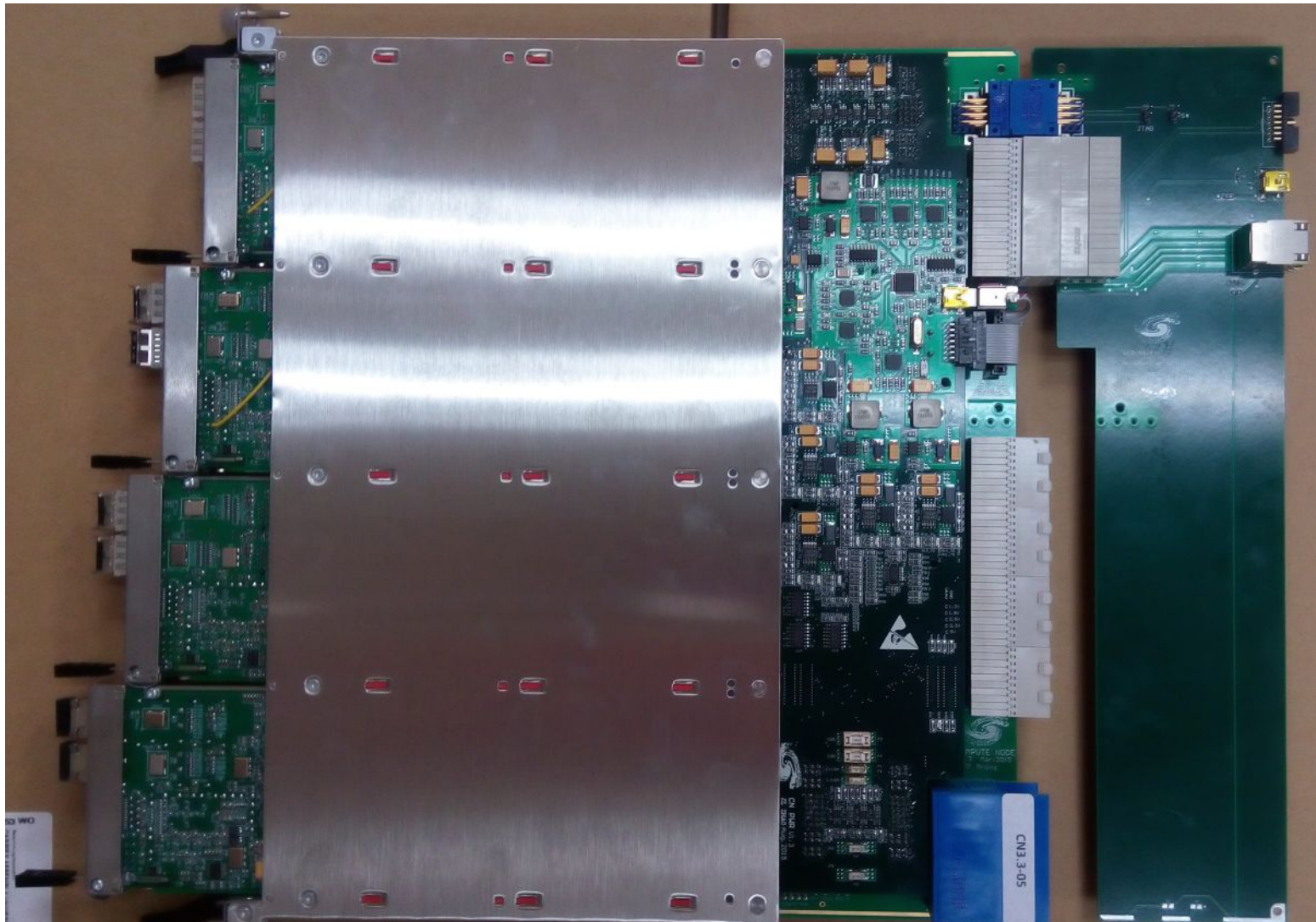
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Outline

- Status of CN Carrier Board

- Status of RTM cards
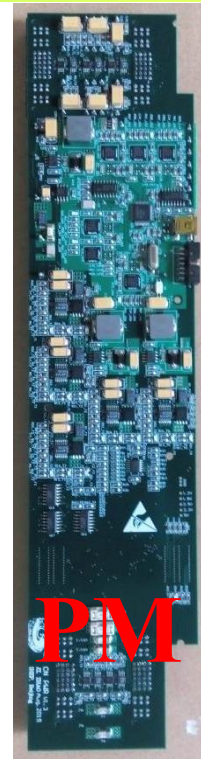
- Status of CN Power Module

- Summary

Compute Node

PXD Valencia workshop

Compute Node

CN Carrier

PM

RTM

64MB Flash

2x6.25Gbps SFP+

xFP V4

V5CFX70T-2

GbE RJ45

2x2GB DDR2   MMC connector

UART

64MB Flash

4x3.125Gbps SFP

xFP V3.1

V5CLX50T-1

2x2GB DDR2   MMC connector

GbE RJ45

UART

CN Status

CN Carrier V3.3

- CN carrier V3.3 finished in May. 2015.
- 5 boards produced. 2 for Giessen, 2 for IHEP, one for Bonn.
- Milan and Jingzhou tested the boards in IHEP in May. 2015.
- It is tested by IHEP and Giessen, and get green light for mass production.

Carrier PowerModule

- PM V1.3 is finished in Oct. 2015.
- Basic function tested in IHEP and 5 cards taken to Giessen.
- IPMC pin assignment and I2C function was checked by Bjoern in Giessen in Dec.2015
- PM V1.3 meet mass production requirement.

CN Status

⊞ RTM

- RTM V1.0 was finished in May. 2015

- Power Connector's position is not suitable, other functions work well.

- RTM V1.0 was upgraded to RTM V1.1

- Power Connector's position is corrected.

- Gigabit Ethernet shielding is enhanced.

- Now every function works well.

Mass production status(1)

- ⌗ Mass production for DATCON
  - ■ xFP V3.1 soldering working finished in Oct. 2015.
  - ■ Now testing work is finished.
  - ■ Next step is installing panel and heat sink.

Mass production status(2)

Mass production for PXD

- All boards are taken back from soldering factory at the beginning of this year.

- Installing and testing work is going on, and if everything goes smoothly, it will be finished at the end of February.

xFP V4

PM V1.3
RTM V1.1

CN carrier V3.3

Summary

- All boards are taken back from soldering factory.

- Testing working will be finished at the end of Feb. 2016.